

Notice of References Cited	Application/Control No. 10/050,179	Applicant(s)/Patent Under Reexamination LIN ET AL.	
	Examiner Magid Y Dimyan	Art Unit 2825	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,581,186	06-2003	Frost et al.	716/1
	B	US-5,604,687	02-1997	Hwang et al.	703/12
	C	US-5,713,666	02-1998	Seelin et al.	374/126
	D	US-5,302,022	04-1994	Huang et al.	374/44
	E	US-6,438,504	08-2002	Mikubo et al.	702/132
	F	US-6,269,277	07-2001	Hershenson et al.	700/97
	G	US-5,468,994	11-1995	Pendse, Rajendra D.	257/693
	H	US-5,202,843	04-1993	Kunimine et al.	703/6
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Lasance, C.J.M., "Thermal Characterization of Electronic Parts with Compact Models: Interpretation, Application, and the Need for a Paradigm Shift" 13th Annual IEEE Semiconductor Thermal Measurement and Management Symposium, Jan. 28-30, 1997, pp. 40-48.
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.